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Scotch Brand High Temperature Masking Tape

#2142

1. Introduction:

This tape is developed for wave solder masking of printed circuit board.

2. Construction:

Backing : Crepe Paper
Adhesive : Acrylate

3. Average Physical Properties :

(JIS-Z-0237)

<u>Item</u>	<u>Unit</u>	<u>Average physical property</u>
Total thickness	mm	0.14
Tensile strength at break	kg/25mm	11.0
Elongation at break	%	9
Adhesion (180 deg peel)	g /25mm	300

*Data are typical value, not recommend for specification purpose.

4. Applications:

Wave solder masking of printed circuit board.

5. Feature and Advantages

Features

Crepe paper backing

Advantages

*High temperature performance
*Slivering resistance after heating
*No solder bath contamination

High temperature acrylate adhesive

*Excellent high temperature performance
*No adhesive residue
*No seepage of solder
*Easy peel off after masking